

SUNDAY, July 19, 2009

Tutorial Shortcourses on Electronic Packaging
Free Admission to all Conference Registrants

8:00 – 10:00

PARALLEL TUTORIALS

Elizabeth A

Tutorial Shortcourse 1

On Chip Hot Spot Remediation with Miniaturized Thermoelectric Coolers
Avram Bar-Cohen, University of Maryland

Elizabeth B

Tutorial Shortcourse 2

Constitutive and Failure Behaviour of SnAgCu Solder Joints
Dhruv Bhate, Intel Corporation
Ganesh Subbarayan, Purdue University

Elizabeth C

Tutorial Shortcourse 3

Thermal Test Methods for Integrated Circuits
Bernie Siegal, Thermal Engineering Associates

Elizabeth D

Tutorial Shortcourse 4A

Identifying the Challenges in the Next Generation of Microprocessors – Part 1
Gamal Refai-Ahmed, AMD
Dereje Agonafer, University of Texas at Arlington;
Bahgat Sammakia, Binghamton University
Kanad Ghose, Binghamton University

10:00 – 10:15

Italian Room

Refreshment Break

10:15 – 12:15

PARALLEL TUTORIALS

Elizabeth A

Tutorial Shortcourse 5

Advances in Modeling and Simulation of Micro- and Nano-Scale Thermal Transport
Cristina Amon, University of Toronto
Jayathi Murthy, Purdue University

Elizabeth B

Tutorial Shortcourse 6

Optical Interactions with MEMS
Leslie Phinney, Sandia National Laboratories

Elizabeth C

Tutorial Shortcourse 7

Thermal Design and Implementation of Robust Liquid Cooling Systems for High Performance Computer Systems

Michael Ellsworth, IBM Corporation

Elizabeth D

Tutorial Shortcourse 4B

Identifying the Challenges in the Next Generation of Microprocessors – Part 2

Gamal Refai-Ahmed, AMD

Dereje Agonafer, University of Texas at Arlington;

Bahgat Sammakia, Binghamton University

Kanad Ghose, Binghamton University

12:15 – 13:45

Lunch on your own

13:45 – 15:45

PARALLEL TUTORIALS

Elizabeth A

Tutorial Shortcourse 8

Micro- and Nano-scale Engineering of Electronic Systems

Ken Goodson, Stanford University

Elizabeth B

Tutorial Shortcourse 9

Future Challenges in Packaging Technology

Raj Master, Microsoft

Elizabeth C

Tutorial Shortcourse 10

Sustainability Modeling and Life-Cycle Assessment

Amip Shah, Hewlett Packard Corporation

Cullen Bash, Hewlett Packard Corporation

Chandrakant Patel, Hewlett Packard Corporation

Elizabeth D

Tutorial Shortcourse 11A

TSV and Other Enabling Technologies for 3D IC Integration and WLP – Part 1

John Lau, Hong Kong University of Science and Technology (HKUST)

15:45 – 16:00

Italian Room

Refreshment Break

16:00 – 18:00

PARALLEL TUTORIALS

Elizabeth A

Tutorial Shortcourse 12

Carbon Nanotube based Nanotechnology

Meyya Meyyappan, NASA Ames Research Center

Elizabeth B

Tutorial Shortcourse 13

Peridynamic Theory - A Multi-scale Physics Based Approach for Failure Prediction in Semiconductor Devices

Erdogan Madenci, University of Arizona

Elizabeth C

Tutorial Shortcourse 14

Challenges and Opportunities in Data Center Thermal and Energy Efficiency Management

Roger Schmidt, IBM Corporation

Madhu Iyengar, IBM Corporation

Elizabeth D

Tutorial Shortcourse 11B

TSV and Other Enabling Technologies for 3D IC Integration and WLP – Part 2

John Lau, Hong Kong University of Science and Technology (HKUST)

18:30 - 19:30

Tower A & B

Opening Reception for All Conference Attendees